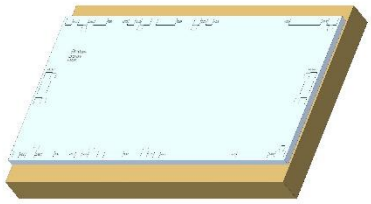
NPA2003-TB-501

27.5 – 31 GHz GaN 34 W Power Amplifier

Product Description

The Nxbeam NPA2003-TB-501 is a Ka-band high power amplifier MMIC fabricated in 0.2um GaN HEMT on SiC mounted on a high thermal conductive heat spreader (tab). The MMIC operates from 27.5 to 31 GHz and provides an average of 34 W saturated output power, 31% PAE, and 24 dB of linear gain. The NPA2003-TB-501 comes in die-on-tab form with RF input and output matched to 50 Ω with DC blocking capacitors for easy system integration. The HEMT devices are fully passivated for reliable operation. Bond pad and backside metallization are Au-based for compatibility with eutectic die attachment methods.



Applications

- Ka-band Satellite Communications
- 5G Infrastructure
- Point-to-Point/Multipoint Digital Radios

Key Features

- Frequency: 27.5 – 31 GHz
- Linear Gain (Ave.): 24 dB
- Psat (Ave.): 34 W
- PAE (Ave.): 31%

Electrical Specifications

Test Condition: Vd = 24 V, Idq = 2.0 A, CW Performance in Fixture, Typical Performance at 25°C

Parameter		Min	Typical	Max	Unit
Frequency		27.5		31	GHz
Gain (Small Signal)	27.5 GHz	22	24	26	dB
	29 GHz		24.3		
	31 GHz		24		
Output Power (at Psat, Pin=26 dBm)	27.5 GHz	44	45.4		dBm
	29 GHz		45.1		
	31 GHz		45		
PAE (at Psat, Pin=26 dBm)	27.5 GHz		32.1		%
	29 GHz		32.0		
	31 GHz		30.2		
Power Gain (at Psat, Pin=26 dBm)	27.5 GHz		17.6		dB
	29 GHz		18.9		
	31 GHz		18.3		
Input Return Loss	27.5 GHz		20		dB
	29 GHz		20		
	31 GHz		11		
Output Return Loss	27.5 GHz		8		dB
	29 GHz		13		
	31 GHz		8		

Maximum Quiescent Bias

Parameter	Max	Unit
Drain Voltage (Vd1, Vd2, Vd3)	28	V
Drain Current (Id1)	264	mA
Drain Current (Id2)	640	mA
Drain Current (Id3)	2112	mA

Maximum quiescent bias represents the operational bias used during reliability life testing. Biasing the part at or below this bias ensures reliability will be bound by the published reliability results.

Absolute Maximum Ratings (Temp. = 25°C)

Parameter	Min	Max	Unit
Drain Voltage (Vd1, Vd2, Vd3)		28	V
Drain Current (Id1)		660	mA
Drain Current (Id2)		1600	mA
Drain Current (Id3)		5250	mA
Gate Voltage (Vg1, Vg2, Vg3)	-8	0	V

Absolute maximum ratings represent the maximum current under power saturation conditions.

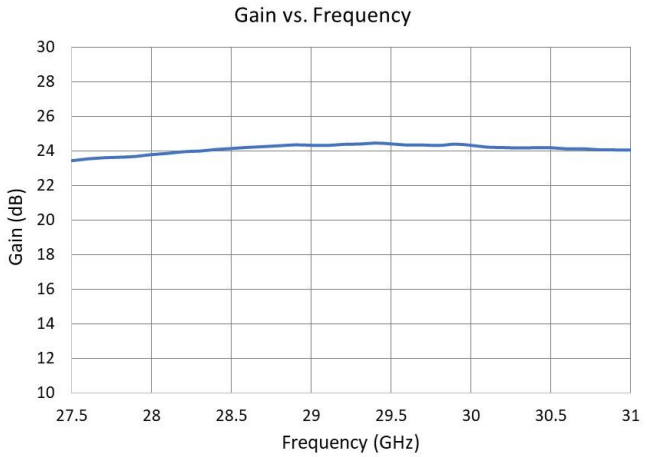
Recommended Quiescent Operating Condition

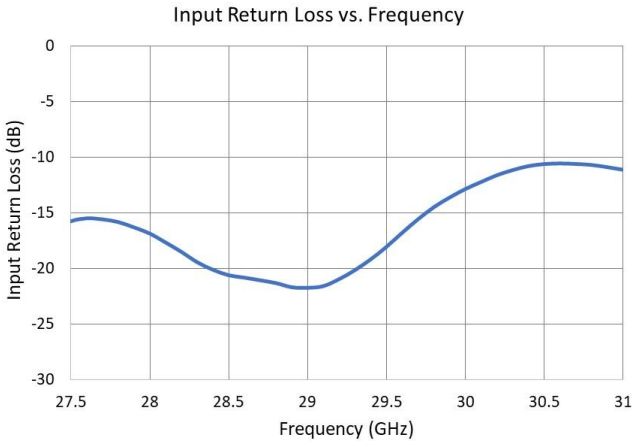
Parameter	Value	Unit
Drain Voltage (Vd)	20 - 28	V
Drain Current (Id1)	up to 264	mA
Drain Current (Id2)	up to 640	mA
Drain Current (Id3)	up to 2112	mA
Gate Voltage (Vg) (Typical Range)	-4	V

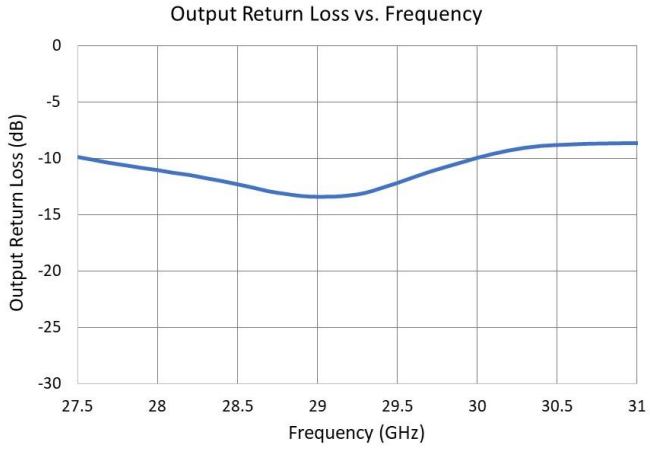
Gate voltage will vary based on desired current per stage

Small Signal Performance

Test Condition: Vd = 24 V, Idq = 2.0 A, (CW Performance in Fixture, Typical Performance at 25°C)



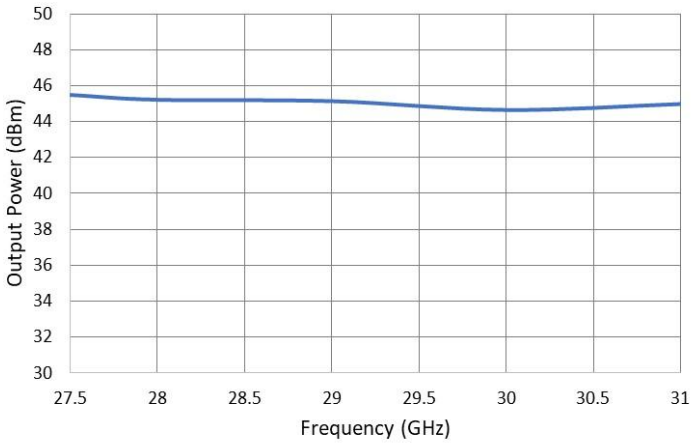




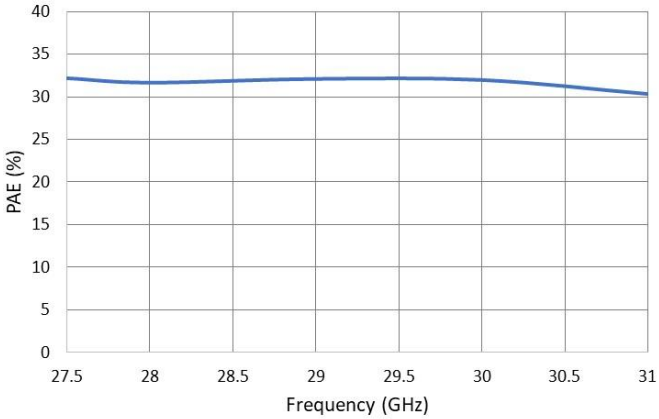
Large Signal Performance

Test Condition: Vd = 24 V, Idq = 2.0 A, Pin = 26 dBm (Psat)
(CW Performance in Fixture, Typical Performance at 25°C)

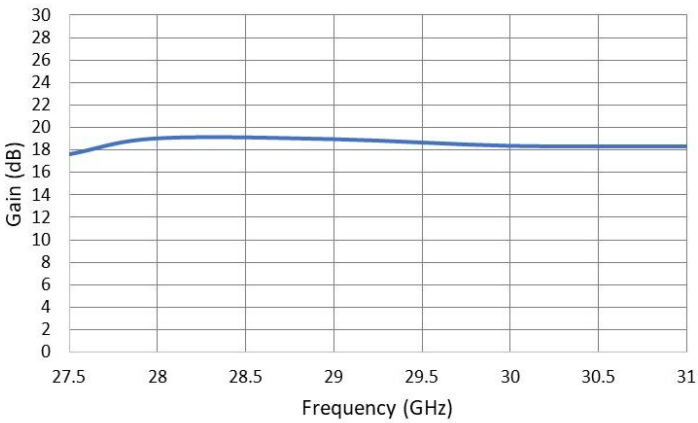
Output Power vs. Frequency (at 26 dBm Pin)



PAE vs. Frequency (at 26 dBm Pin)



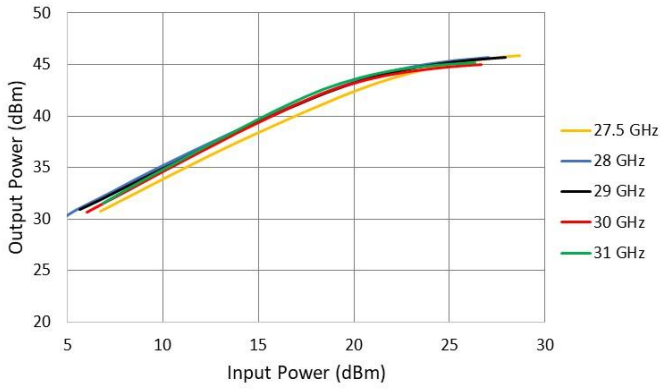
Gain vs. Frequency (at 26 dBm Pin)



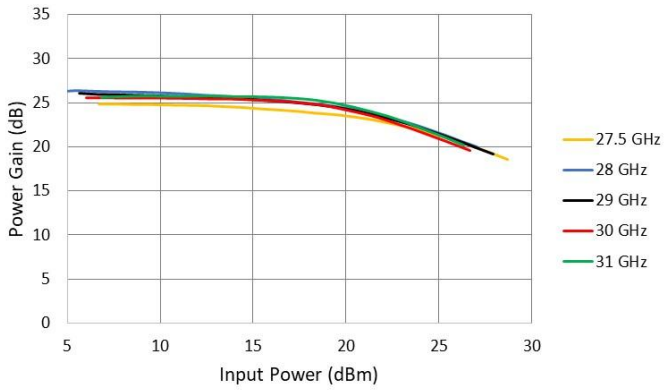
Large Signal Performance

Test Condition: Vd = 24 V, Idq = 2.0 A,
(CW Performance in Fixture, Typical Performance at 25°C)

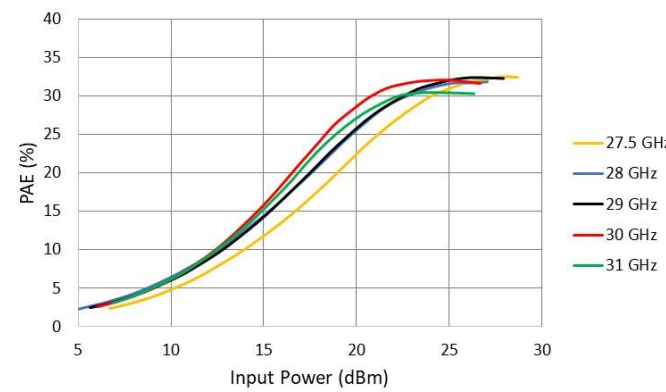
Output Power vs. Input Power vs. Frequency



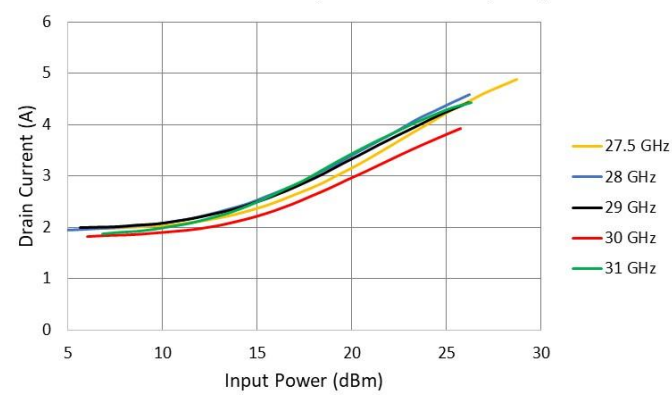
Power Gain vs. Input Power vs. Frequency



PAE vs. Input Power vs. Frequency



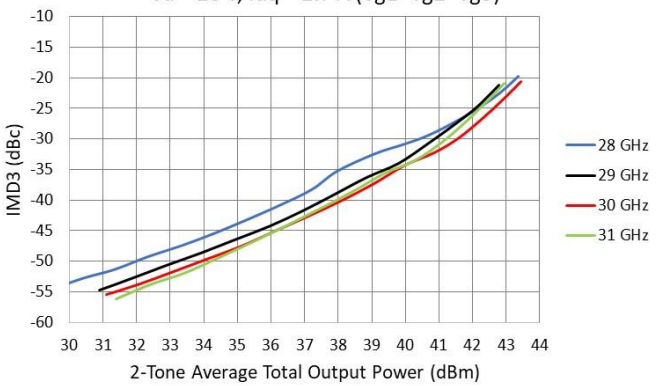
Drain Current vs. Input Power vs. Frequency



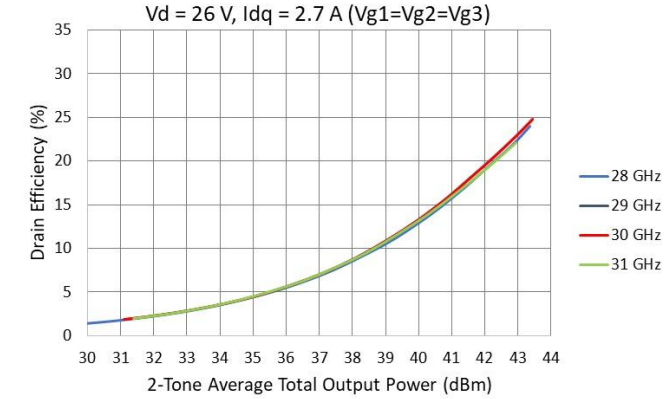
2-Tone Linearity Performance

10 MHz Tone Spacing , CW Performance in Fixture, Typical Performance at 25°C,

IMD3 vs. 2-Tone Output Power vs. Frequency
Vd = 26 V, Idq = 2.7 A (Vg1=Vg2=Vg3)

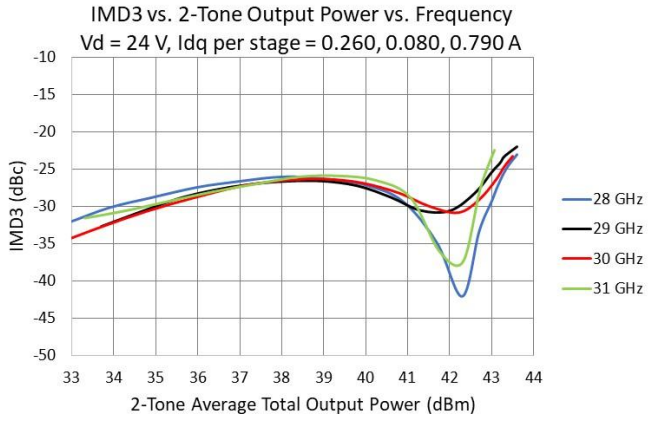


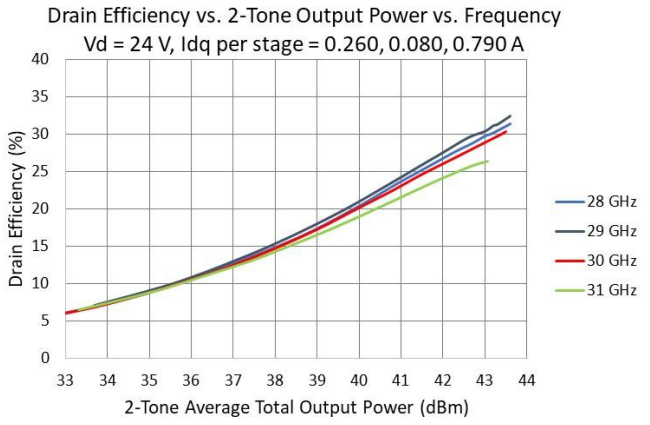
Drain Efficiency vs. 2-Tone Output Power vs. Frequency
Vd = 26 V, Idq = 2.7 A (Vg1=Vg2=Vg3)

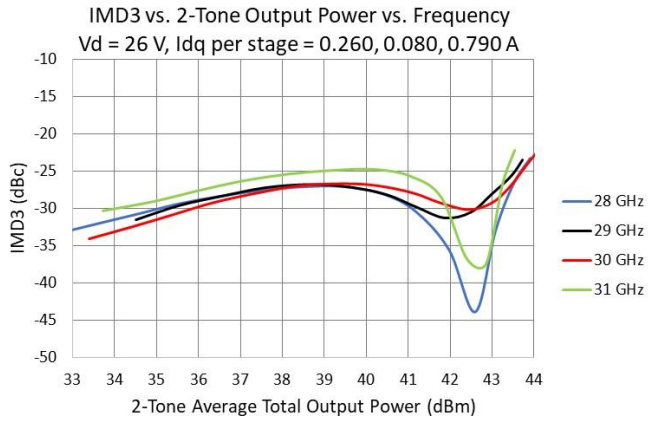


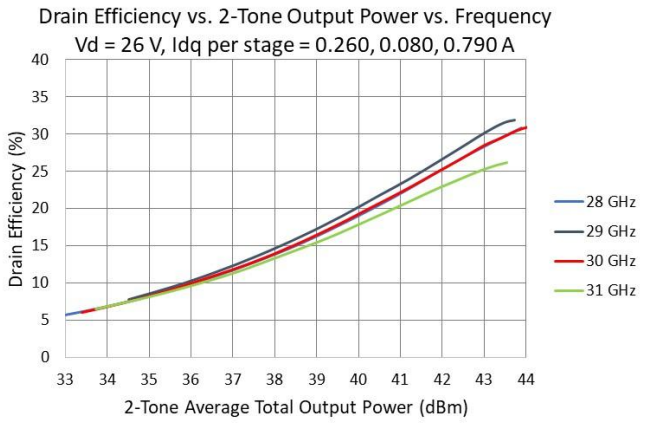
2-Tone Linearity Performance

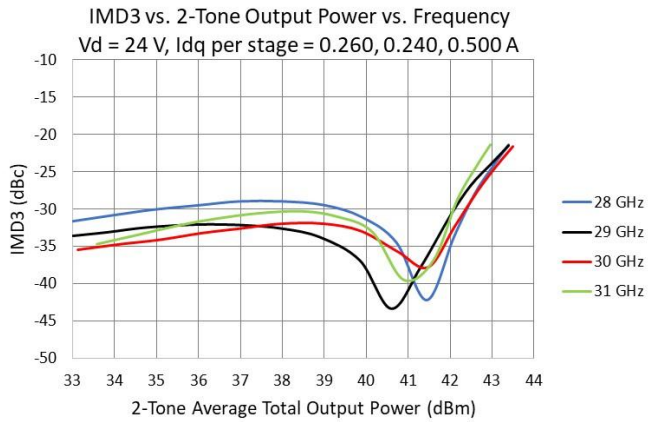
10 MHz Tone Spacing , CW Performance in Fixture, Typical Performance at 25°C,
Gate Voltages Biased Separately

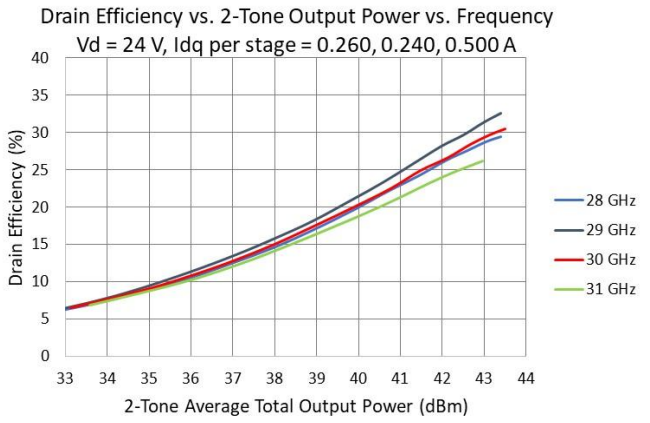






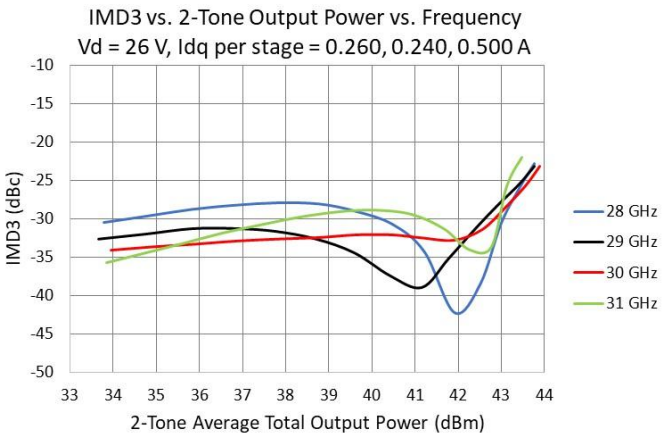


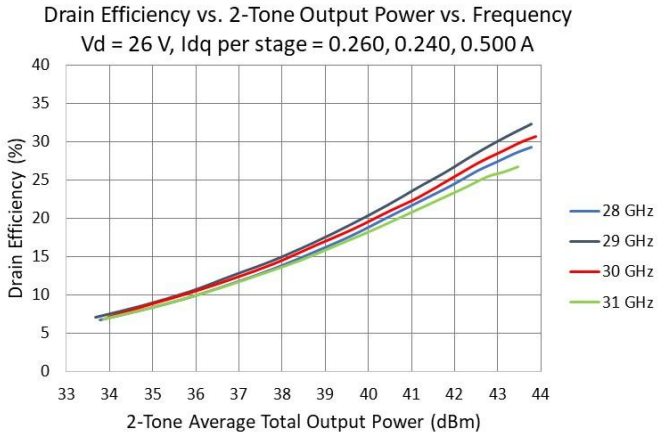


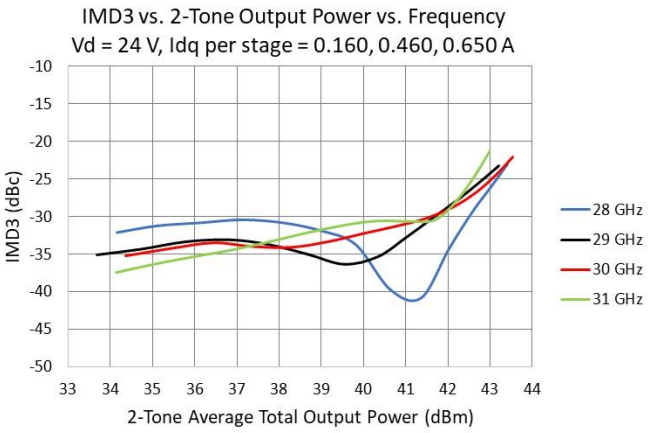


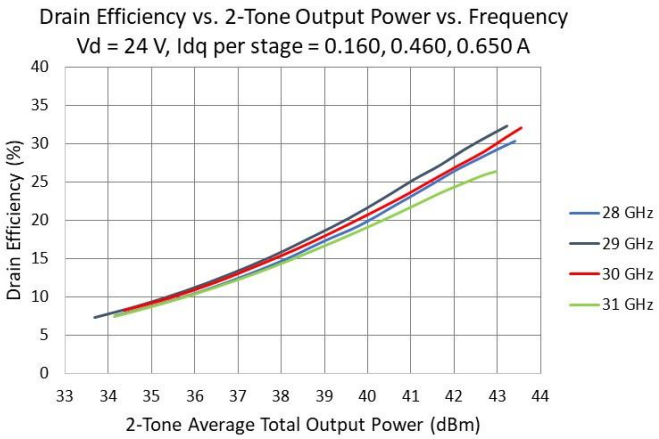
2-Tone Linearity Performance

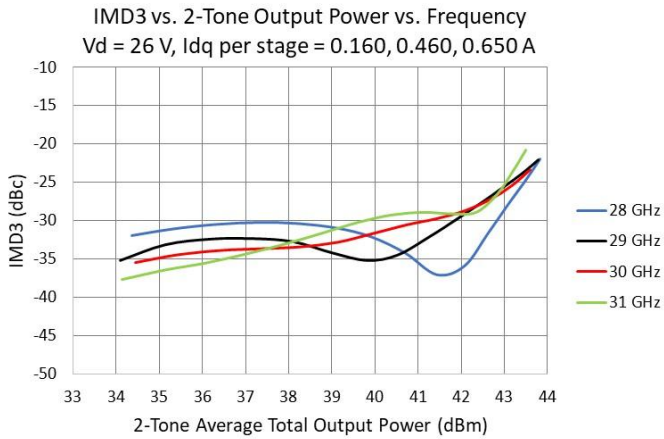
10 MHz Tone Spacing , CW Performance in Fixture, Typical Performance at 25°C,
Gate Voltages Biased Separately

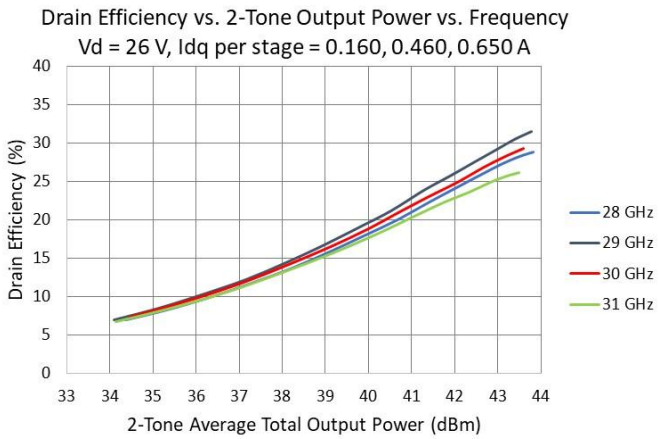






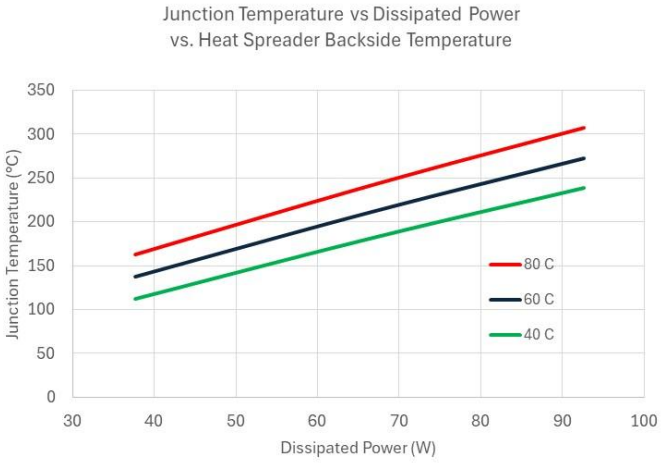


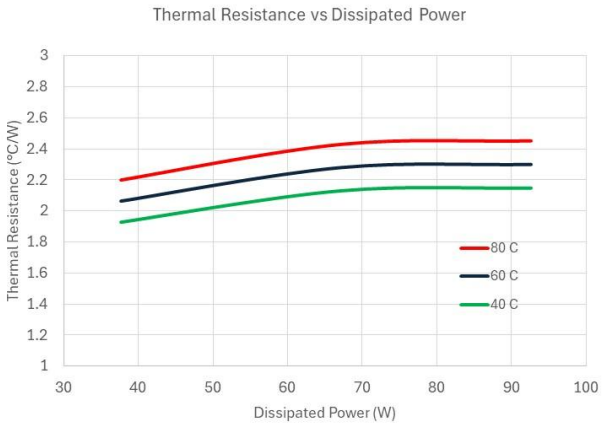




Thermal Information

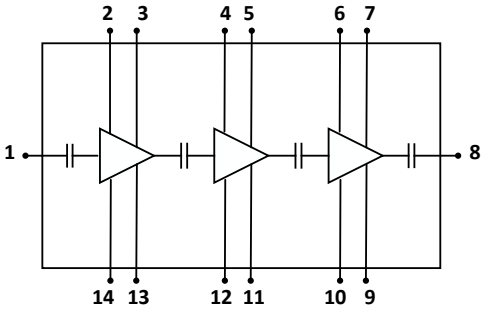
Junction Temperature and Thermal Resistance Referenced From Backside of Heat Spreader





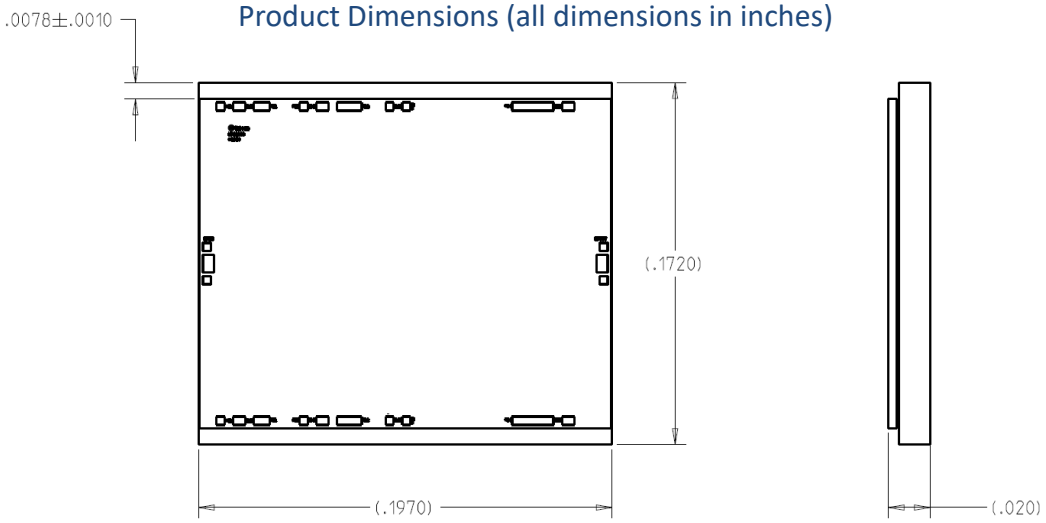
Note 1: Mean time to failure per junction temperature information can be found in the following document: Nxbeam_GaN20MMIC_Reliability.pdf

Circuit Block Diagram



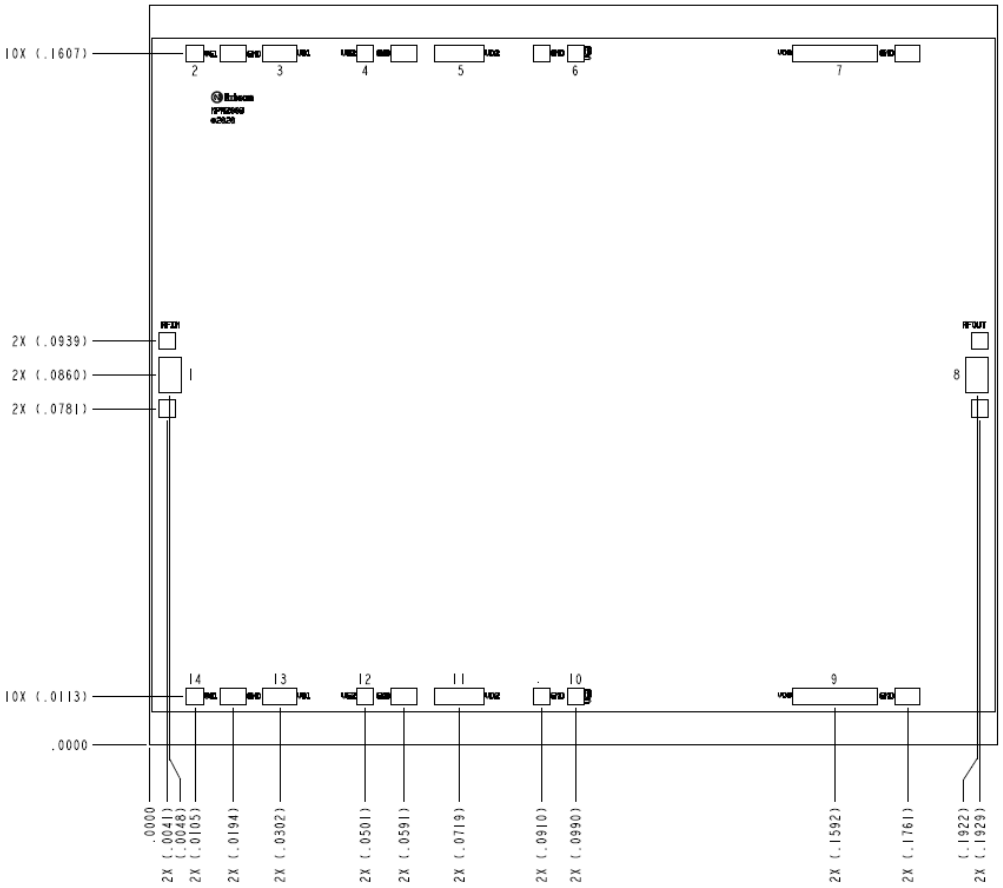
Pin number information detailed under Die Size and Bond Pad Information

Product Dimensions (all dimensions in inches)



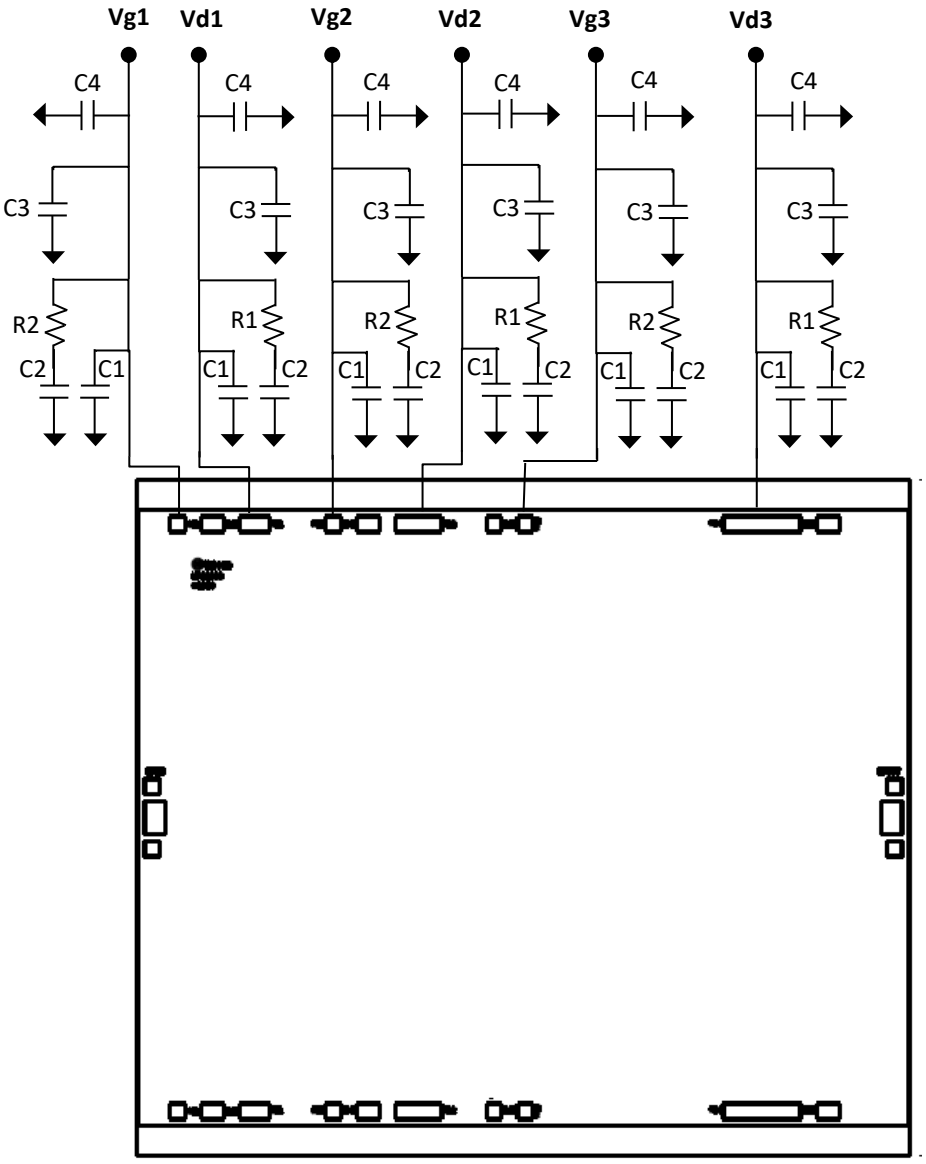
Die Size and Bond Pad Information

TABLE I: INTERFACE IDENTIFICATION			
ID	FUNCTION	PAD NUMBER	PAD SIZE (MICRONS)
RFIN	RF INPUT	1	134 X 208
RFOUT	RF OUTPUT	8	134 X 208
VG1	GATE VOLTAGE - STAGE 1 (-8V MIN, 0V MAX)	2,14	100 X 100
VD1	DRAIN VOLTAGE - STAGE 1 (0V MIN, 28V MAX)	3,13	196 X 100
VG2	GATE VOLTAGE - STAGE 2 (-8V MIN, 0V MAX)	4,12	100 X 100
VD2	DRAIN VOLTAGE - STAGE 2 (0V MIN, 28V MAX)	5,11	296 X 100
VG3	GATE VOLTAGE - STAGE 3 (-8V MIN, 0V MAX)	6,10	96 X 100
VD3	DRAIN VOLTAGE - STAGE 3 (0V MIN, 28V MAX)	7,9	500 X 100



Suggested Off-Chip Components

The following diagram shows the recommended off-chip components to be used with the NPA2003-TB-501. The off-chip components should be duplicated on both top and bottom sides of the chip and located as close to the chip as possible. Bias should be applied to the chip from both sides. Please consult with Nxbeam on other off-chip network variations.



Recommended Off-Chip Component Values

Capacitor	Value
C1	100 pF
C2	0.01 µF
C3	1 µF
C4	10 µF

Resistor	Value
R1	1 Ω
R2	10 Ω

Assembly Process

- The heat spreader is gold plated and can be mounted using either a high thermal conductive epoxy or solder attachment.
- Maximum recommended temperature during product attachment is 260 °C for not more than 60 seconds.
- This product contains metal air bridges so caution should be taken when handling to avoid damage.

Bias Information

Bias-up Procedure:

1.) It is recommended that voltage and current limits are set on the voltage supply's prior to biasing the product.
2.) Ensure power supplies are properly grounded to the product test fixture.
3.) Apply a negative gate voltage of -7V to Vg1, Vg2, and Vg3 to ensure all devices are pinched off.
4.) Gradually increase the drain bias voltage (Vd1, Vd2, Vd3) to the desired bias level but not to exceed the maximum voltage of 28 V.
5.) Gradually increase the gate voltages (Vg1, Vg2, Vg3) while monitoring the drain current until the desired drain current in each stage is achieved.
6.) Apply RF signal.

Bias-down Procedure:

1.) Turn off RF signal.
2.) Gradually decrease Vg1, Vg2, and Vg3 down to -7 V.
3.) Gradually decrease the drain voltages (Vd1, Vd2, Vd3) down to 0 V.
4.) Gradually increase gate voltages (Vg1, Vg2, Vg3) to 0 V.
5.) Turn off supply voltages

ESD Sensitive Product

Important Information

The product represented by this datasheet is controlled by US law for export under the ECCN 3A001.b.2.c. The purchaser of these product, whether in the US or abroad, is responsible for compliance with all US laws regarding export, transfer, or re-transfer of this product. For more information, please refer to the Export Administration Regulations at www.bis.doc.gov. Nxbeam reminds you that it is your responsibility to ascertain your export compliance obligations and to comply with all applicable laws and regulations.

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